



Material Content Data Sheet



Sales Product Name		BSC0911ND		Issued		19. July 2018		
MA#		MA001013774						
Package		PG-TISON-8-3		Weight*		101.93 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.133	1.11	1.11	11114	11114
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		101	
	non noble metal	zinc	7440-66-6	0.041	0.04		403	
	non noble metal	iron	7439-89-6	0.822	0.81		8061	
wire	non noble metal	copper	7440-50-8	33.360	32.73	33.59	327303	335868
	noble metal	gold	7440-57-5	0.069	0.07	0.07	672	672
	encapsulation	organic material	carbon black	1333-86-4	0.092	0.09		898
plastics	plastics	epoxy resin	-	4.715	4.63		46263	
	inorganic material	silicondioxide	60676-86-0	40.973	40.19	44.91	401992	449153
	leadfinish	non noble metal	tin	7440-31-5	1.122	1.10	1.10	11006
plating	noble metal	silver	7440-22-4	0.186	0.18	0.18	1823	1823
solder	noble metal	silver	7440-22-4	0.043	0.04		423	
	non noble metal	tin	7440-31-5	0.034	0.03		338	
	non noble metal	lead	7439-92-1	1.646	1.62	1.69	16153	16914
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.01		52	
	non noble metal	zinc	7440-66-6	0.021	0.02		208	
	non noble metal	iron	7439-89-6	0.424	0.42		4163	
	non noble metal	copper	7440-50-8	17.228	16.90	17.35	169027	173450
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com